

Features

- 1W Power Dissipation on FR-4 PCB
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**
<https://www.diodes.com/quality/product-definitions/>
- **An automotive-compliant part is available under separate datasheet (DFLZ5V1Q - DFLZ39Q)**

Mechanical Data

- Package: PowerDI[®]123
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.01 grams (Approximate)



Top View

Ordering Information (Note 4)

Part Number	Package	Packing	
		Quantity	Carrier
(Type Number)-7*	PowerDI123	3,000	Tape & Reel
(Type Number)-13**	PowerDI123	10,000	Tape & Reel

* Add "-7" to the appropriate type number in Electrical Characteristics Table. Example: 16V Zener = DFLZ16-7

** Add "-13" to the appropriate type number in Electrical Characteristics Table. Example: 16V Zener = DFLZ16-13

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



Fxx = Product Type Marking Code
(See Electrical Characteristics Table)
YM = Date Code Marking
Y = Year (ex: K = 2023)
M = Month (ex: 9 = September)

Date Code Key

Year	2014	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	B	K	L	M	N	O	P	R	S	T	U
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 200mA	V _F	1.2	V

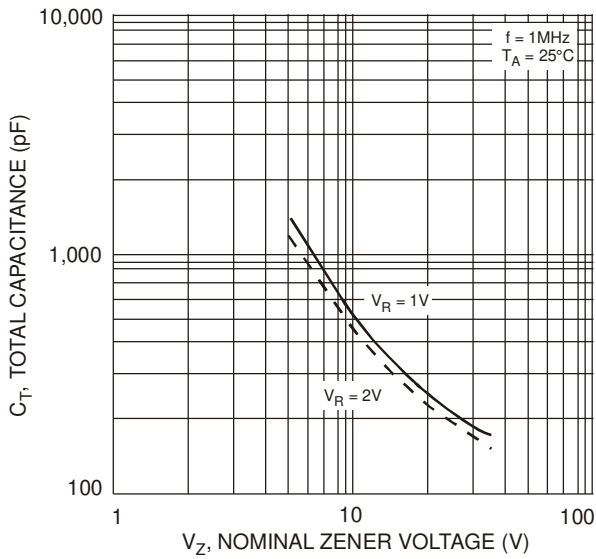
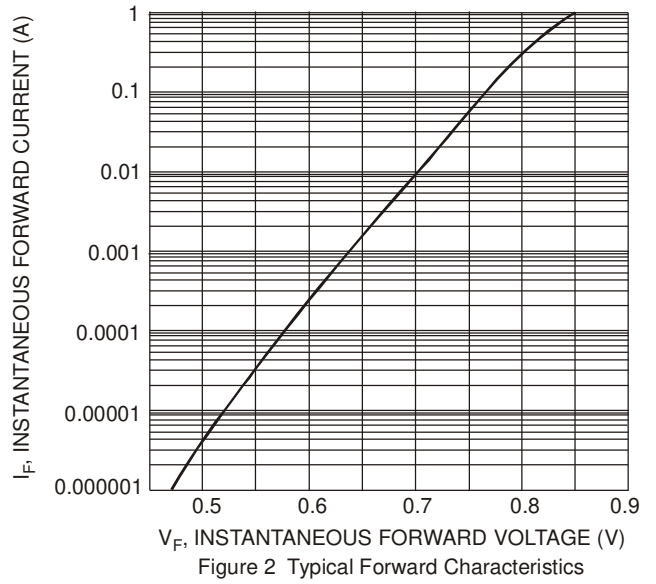
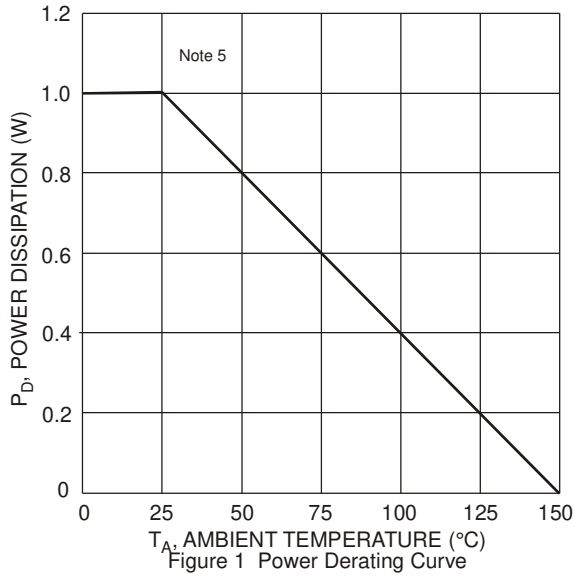
Thermal Characteristics

Characteristic	Symbol	Typ	Value	Unit
Power Dissipation (Note 5)	P _D	—	1.0	W
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	110	—	°C/W
Thermal Resistance Junction to Soldering Point (Note 6)	R _{θJS}	—	9	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	—	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Type Number	Marking Codes	Zener Voltage Range (Note 7)				Zener Impedance		Maximum Reverse Current (Note 7)		Temperature Coefficient @ I _{ZTC} %/°C	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}		I _R	@ V _R	Min	Max
		Nom (V)	Min (V)	Max (V)	mA	Typ (Ω)	Max (Ω)	μA	V		
DFLZ5V1	FHK	5.1	4.8	5.4	100	2	6	2.5	1	-0.08	0.02
DFLZ5V6	FHL	5.6	5.2	6.0	100	1	4	10	2	-0.04	0.04
DFLZ6V2	FHN	6.2	5.8	6.6	100	1	3	5	2	-0.01	0.06
DFLZ6V8	FHO	6.8	6.4	7.2	100	1	3	5	3	0	0.07
DFLZ7V5	FHQ	7.5	7.0	7.9	100	1	2	5	3	0	0.07
DFLZ8V2	FHR	8.2	7.7	8.7	100	1	2	5	3	0.03	0.08
DFLZ9V1	FHT	9.1	8.5	9.6	50	1	4	5	5	0.03	0.08
DFLZ10	FHU	10	9.4	10.6	50	1	4	5	7.5	0.05	0.09
DFLZ11	FHV	11	10.4	11.6	50	1	7	4	8.2	0.05	0.10
DFLZ12	FHW	12	11.4	12.7	50	1	7	3	9.1	0.05	0.10
DFLZ13	FHX	13	12.4	14.1	50	1	10	2	10	0.05	0.10
DFLZ15	FHZ	15	13.8	15.6	50	1	10	1	11	0.05	0.10
DFLZ16	FJA	16	15.3	17.1	25	1	15	1	12	0.06	0.11
DFLZ18	FJF	18	16.8	19.1	25	2	15	1	13	0.06	0.11
DFLZ20	FJG	20	18.8	21.2	25	3	15	1	15	0.06	0.11
DFLZ22	FJK	22	20.8	23.3	25	3	15	1	16	0.06	0.11
DFLZ24	FJL	24	22.8	25.6	25	2	15	1	18	0.06	0.11
DFLZ27	FJN	27	25.1	28.9	25	3	15	1	20	0.06	0.11
DFLZ30	FJQ	30	28	32	25	8	15	1	22	0.06	0.11
DFLZ33	FJR	33	31	35	25	5	15	1	24	0.06	0.11
DFLZ36	FJS	36	34	38	10	5	40	1	27	0.06	0.11
DFLZ39	FJT	39	37	41	10	5	40	1	30	0.06	0.11

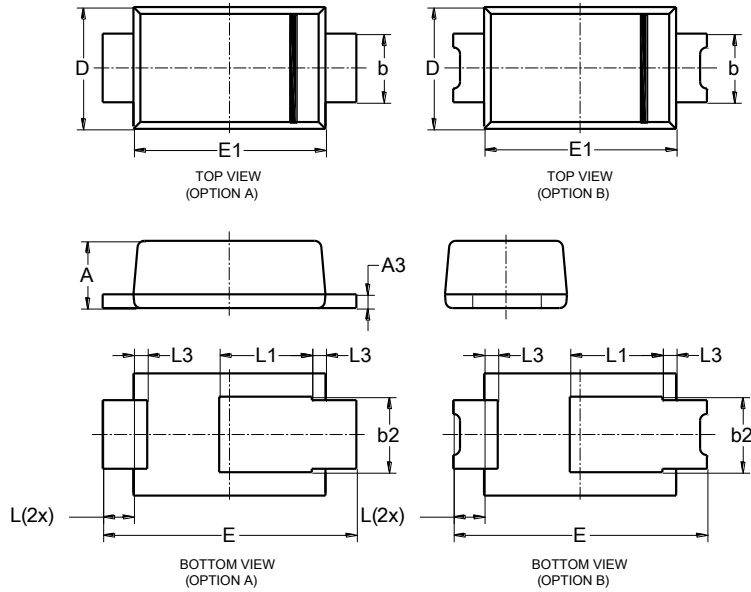
- Notes:
5. Device mounted on 1.5" x 1.5", FR-4 PCB; 2 oz. Cu with 1"x1" pad layout.
 6. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 7. Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123

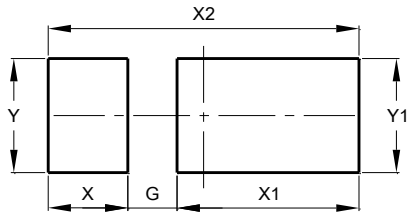


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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